

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patents issued thereon.

Signature:
Sole or First Joint Inventor: Yi-Chuan Ding
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R.O.C.



As the below named inventor, I hereby declare that:

the specification of which

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My residence, post office address and citizenship are as stated below next to my name and that believe I am an original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

FLIP CHIP PROCESS

is attached hereto					
was filed on	·				
as Application Ser	ial No	and was amended on		·	
I hereby state th	at I have reviewed a	nd understand the conten	ts of the at	bove-ident	
ecification, including t	the claims, as amended	d by any amendment referre	d to above.		
I acknowledge the	e duty to disclose info	rmation which is material to	the patent	ability of	
plication in accordanc	ce with Title 37, Code o	f Federal Regulations, § 1.5	56(a).		
I hereby claim fore	eign priority benefits und	der Title 35, Untied States C	ode, § 119	of any for	
plication(s) for patent	or inventor's certificate	listed below and have also i	dentified bel	ow any for	
plication for patent or	inventor's certificate ha	ving a filing date before that	of the applic	ation on w	
ority is claimed:					
or Foreign Application	n(s):				
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Number	Country	Date Filed(yyyy/mm/dd)	Yes	No	
89127631	Taiwan, R.O.C.	2000/12/22	Х	-	
		and/or agent(s) to prosect ark Office connected therew		ication an	
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